







SolidMatrix[®] Surface Mount Fuses HI Series (High Inrush), 0603 Size



Clearing Time Characteristics:

% of Current Rating	Clearing time at 25°C		
100%	4 hours min.		
200%	1 second min.	60 seconds max.	
1000% (1-5A)	0.0002 seconds min.	0.02 seconds max.	

Agency Approval:

Recognized Under the Components Program of UL. File Number: E232989.

Patents:

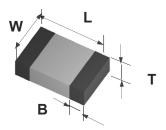
Patent numbers "US6,034,589", "US6,602,766", "US7,268,661 B2", "ZL00134544.3", "ZL02114719.1", "ZL200410104280.7", "ZL201020551360.8", "ZL201010299185.2", "ZL201220030614.0", "ZL201210020693.1".

Features:

- High inrush current withstanding capability
- Ceramic Monolithic structure
- Silver fusing element and silver termination with nickel and tin plating
- Symmetrical design with marking on both sides (optional)
- Operating temperature range: -55°C to +125°C (with derating)

Shape and Dimensions:

Unit	Inch	mm
L	0.063 ± 0.006	1.60 ± 0.15
W	0.031 ± 0.006	0.80 ± 0.15
Т	0.031 ± 0.006	0.80 ± 0.15
В	0.014 ± 0.006	0.36 ± 0.15



Ordering Information:

Part Number	Current Rating (A)	Voltage Rating (VDC)	Interrupting Ratings	Nominal Cold DCR(Ω) ¹	Nominal I ² t (A ² s) ²	Marking (Optional) ³
F0603HI1000V032T	1.0	32		0.210	0.08	E
F0603HI1500V032T	1.5	32	1	0.101	0.11	G
F0603HI2000V032T	2.0	32		0.057	0.24	I
F0603HI2500V032T	2.5	32	50 4 -44-4	0.042	0.56	J
F0603HI3000V032T	3.0	32	50 A at rated voltage	0.030	0.72	K
F0603HI3500V032T	3.5	32]	0.022	1.10	L
F0603HI4000V032T	4.0	32		0.018	2.08	M
F0603HI4500V032T	4.5	32		0.014	2.63	Т
F0603HI5000V032T	5.0	32]	0.013	3.25	N
F0603HI6000V032T	6.0	32		0.010	4.00	0
F0603HI7000V032T	7.0	32	80 A at rated voltage	0.008	5.00	Р
F0603HI8000V032T	8.0	32		0.006	7.00	R

^{1.} Measured at \leq 10% rated current and 25°C ambient.

^{2.} Melting I²t at 1000% of current rating.

^{3.} Green Marking Character Code.



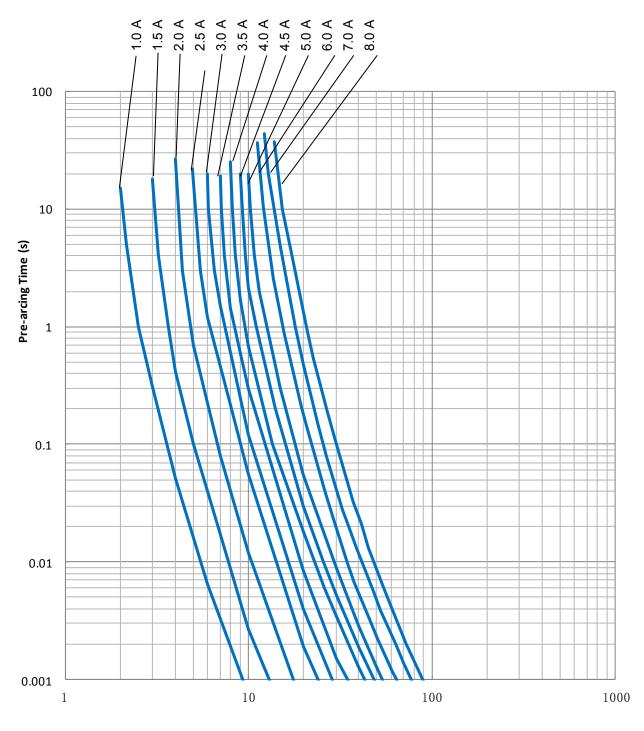






SolidMatrix[®] Surface Mount Fuses HI Series (High Inrush), 0603 Size

Average Pre-arcing Time Curves:





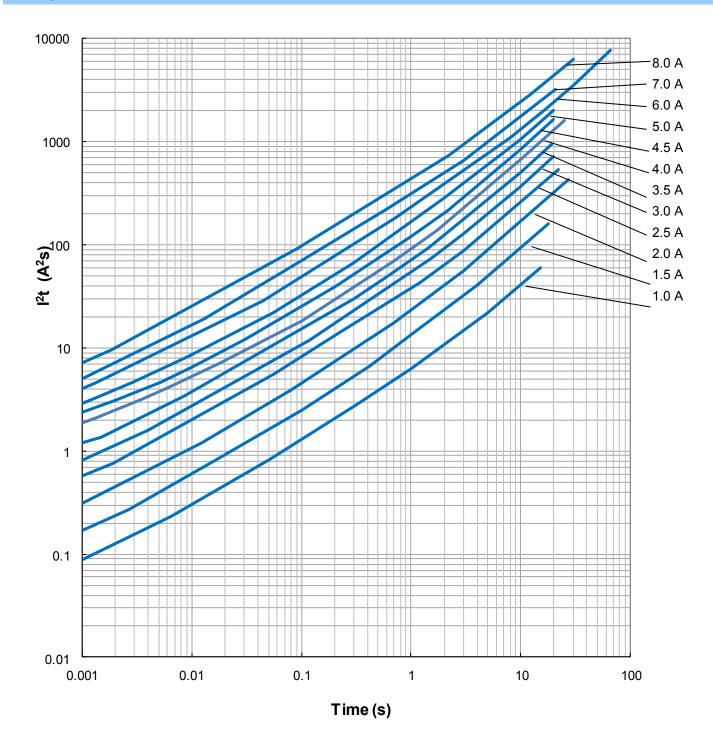






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Average I²t vs. t Curves:











AirMatrix[®] Surface Mount Fuses

Product Identification:

AF2 1.00 V125 T M

(1) (2) (3) (4) (5)

(1) Series Code: AF2

(2) Current Rating Code: 1.00—1.00A
(3) Voltage Rating Code: V125—125VDC
(4) Package Code: T - Tape & Reel, B - Bulk

(5) Marking Code: M - With Marking

AF 1206 F 2.00 T M

(1) (2) (3) (4) (5) (6)

(1) Series Code: AF—AF Series, MF—MF Series

(2) Size Code: Standard EIA Chip Sizes

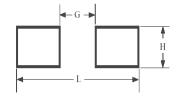
(3) Time/Current Characteristic: F(4) Current Rating: 2.00—2.00A

(5) Package Code: T - Tape & Reel, B - Bulk

(6) Marking Code: M - With Marking

Recommended Land Pattern:

	Al	F2	AF1206		MF2410		MF1210	
	Inch	mm	Inch	mm	Inch	mm	Inch	mm
L	0.338	8.60	0.173	4.40	0.338	8.60	0.170	4.40
G	0.118	3.00	0.059	1.50	0.118	3.00	0.070	1.70
Н	0.124	3.15	0.071	1.80	0.110	2.80	0.110	2.70



Packaging:

Chip Size	Parts on 7 inch (178 mm) Reel	
2410 (6125)	2,000	
1210 (3225)	2,500	
1206 (3216)	3,500	

Storage:

The maximum ambient temperature shall not exceed 35°C . Storage temperatures higher than 35°C could result in the deformation of packaging materials.

The maximum relative humidity recommended for storage is 75%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components.

Sealed vacuum foil bags with desiccant should only be opened prior to use.

The products should not be stored in areas where harmful gases containing sulfur or chlorine are present.







AirMatrix[®] Surface Mount Fuses

Fuse Selection and Temperature De-rating Guideline:

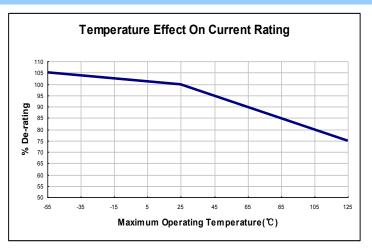
The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25°C, the fuse shall be "derated".

To select a fuse from the catalog, the following rule may be followed:

Catalog Fuse Current Rating = Nominal Operating Current / 0.75 / % De-rating at the maximum operating temperature.

Example: At maximum operating temperature of 65°C, % De-rating is 90%. The nominal operating current is 4 A. The current rating for fuse selected from the catalog shall be:

4 / 0.75 / 90% = 5.9 or 6.3 A.



Environmental Tests:

Reliability Test	Test Condition and Requirement	Test Reference	
Reflow & Bend	3 reflows at 245°C followed by a 2 mm bend, 20% DCR change max. (10% for ≤ 1 A), no mechanical damage	Refer to AEM QIQ034 ,QIQ048	
Solderability	245°C, 5 seconds, new solder coverage 90% minimum	MIL-STD-202 Method 208	
Soldering Heat Resistance	260°C, 10 seconds, 20% DCR change max. (10% for ≤ 1 A), new solder coverage 75% minimum	MIL-STD-202 Method 210	
Life	25°C, 2000 hours, 80% rated current (75% for < 1 A), voltage drop change≤ ±20%	Refer to AEM QIQ106	
Thermal Shock	-65°C to +125°C, 100 cycles, 10% DCR change max., no mechanical damage	MIL-STD-202 Method 107	
Mechanical Vibration	5 – 3000 Hz, 0.4 inch double amplitude or 30 G peak, 10% DCR change max., no mechanical damage	MIL-STD-202 Method 204	
Mechanical Shock	1500 G, 0.5 milliseconds, half-sine shocks, 10% DCR change max., no mechanical damage	MIL-STD-202 Method 213	
Salt Spray	5% salt solution, 48 hour exposure, 10% DCR change max., no excessive corrosion	MIL-STD-202 Method 101	
Moisture Resistance	10 cycles, 15% DCR change max., no excessive corrosion	MIL-STD-202 Method 106	





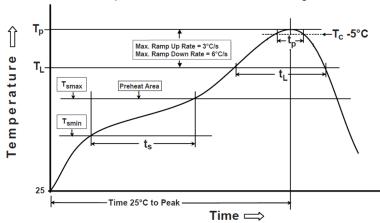




AirMatrix® Surface Mount Fuses

Soldering Temperature Profile:

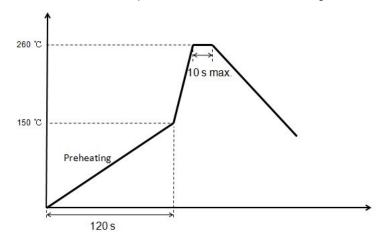
* Recommended Temperature Profile for Reflow Soldering



Profile Feature	Pb-Free Assembly	
Preheat/Soak Temperature Min (T _{smin}) Temperature Max(T _{smax}) Time(t _s) from (T _{smin} to T _{smax})	150°C 200°C 60~120 seconds	
Ramp-uprate (T _L to T _p)	3°C/second max.	
Liquidous temperature(T _L) Time(t _L) maintained above T _L	217°C 60~150 seconds	
Peak package body temperature (T _p)	260°C	
Time (t _p)*within 5°C of the specified classification temperature (T _c)	30 seconds *	
Ramp-down rate (T _p to T _L)	6°C/second max.	
Time 25°C to peak temperature	8 minutes max.	
* T. I	(T) :- 1. C - 1	

^{*} Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum

* Recommended Temperature Profile for Wave Soldering



Disclaimer:

Specifications are subject to change without notice. AEM products are designed for specific applications and should not be used for any purpose (including, without limitation, automotive, aerospace, medical, life-saving applications, or any other application which requires especially high reliability for the prevention of such defect as may directly cause damage to the third party's life, body or property) not expressly set forth in applicable AEM product documentation. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Warranties granted by AEM shall be deemed void for products used for any purpose not expressly set forth in applicable AEM product documentation. AEM shall not be liable for any claims or damages arising out of products used in applications not expressly intended by AEM as set forth in applicable AEM product documentation. The sale and use of AEM products is subject to AEM terms and conditions of sale. Please refer to AEM's website for updated catalog and terms and conditions of sale.